

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	("0154592" "0179329" "4190854" "6237218" "6317023" "6631551"). PN.	USPAT; EPO; JPO	OR	ON	2005/11/11 09:47
L2	16	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position feature align\$4) and (tungsten glass) and laminat\$3	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/11 09:53
L3	1	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position feature align\$4 register) and tungsten with glass	USPAT; EPO; JPO	OR	ON	2005/11/11 10:01
L4	1	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position feature align\$4 register mark) and (w tungsten) with (borosilicates silicates borates glass)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:04
L5	3	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray and (reference mark fiducial) near4 (location position feature align\$4 register mark) same (w tungsten) with (borosilicates silicates borates glass)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:18
L6	67	(reference mark fiducial) near4 (location position feature align\$4 register mark) same (w tungsten) with (borosilicates silicates borates glass)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:09
L7	8	(reference mark fiducial) near4 (location position feature align\$4 register mark) same tungsten with (borosilicates silicates borates glass)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:17
L8	8	(reference mark fiducial) near4 (location position feature align\$4 register mark) same tungsten with (borosilicates silicates borates glass additive)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:17
L11	2	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray same (reference mark fiducial) near4 (location position feature align\$4 register mark) with tungsten	USPAT; EPO; JPO	OR	ON	2005/11/11 10:20

L14	23	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position feature align\$4 register mark) and tungsten	USPAT; EPO; JPO	OR	ON	2005/11/11 10:25
L15	15	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position feature align\$4 register mark) and x\$1ray with tungsten	USPAT; EPO; JPO	OR	ON	2005/11/11 10:23
L16	43	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) with x\$1ray and x\$1ray with (reference mark fiducial) near4 (location position align\$4 register feature) and align\$4 with x\$1ray	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/11 10:31
L17	12	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position align\$4 register feature) and align\$4 with x\$1ray and laminat\$3	USPAT; EPO; JPO	OR	ON	2005/11/11 10:33
L18	6	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position align\$4 register feature) and align\$4 with laminat\$3	USPAT; EPO; JPO	OR	ON	2005/11/11 10:38
L19	9	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4) near2 (foil layer film)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:41
L20	1	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and x\$1ray with (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film) and (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 10:45
L21	3	("20010026638" "5590170" "6552352").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/11 10:44

L22	1	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) with (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film) and (embed\$4 encapsulat\$3) and x\$1ray	USPAT; EPO; JPO	OR	ON	2005/11/11 10:45
L23	49	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film) and (embed\$4 encapsulat\$3) and x\$1ray	USPAT; EPO; JPO	OR	ON	2005/11/11 10:46
L24	3	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) same x\$1ray and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film) and (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 12:09
L27	522	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film) and (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 12:23
L28	55	"29"/\$.cls. and 27	USPAT; EPO; JPO	OR	ON	2005/11/11 12:16
L29	6	("4870746" "5708569" "5800575" "6610417" "6631551" "6734542").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/11 12:11
L30	4	("5172304" "6038133" "6060150" "6160526").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/11 12:13
L31	10	("4241103" "4602421" "4687543" "4797508" "4870746" "5010641" "5079069" "5116641" "5155655" "5347258").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/11 12:13
L32	35	"361"/\$.cls. and 27 not 28	USPAT; EPO; JPO	OR	ON	2005/11/11 12:18
L33	24	"174"/\$.cls. and 27 not 28	USPAT; EPO; JPO	OR	ON	2005/11/11 12:18

L34	10	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) with (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film) same (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 12:28
L35	6	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) with (reference mark fiducial) near4 (location position align\$4 register feature) and laminat\$3 and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) with (component device) and (component device) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 12:29
L36	9	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) with (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) with (component device) and (component device) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 13:18
L37	20	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) with (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (component device) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 13:20
L38	516	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) with (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate)	USPAT; EPO; JPO	OR	ON	2005/11/11 13:21
L39	2	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) with (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) same (dielectric insulat\$3 resin) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 13:22

L40	39	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) with (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 13:55
L41	5	("3324014" "4306925" "4790902" "5017271").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/11 13:30
L42	35	("3324014").URPN.	USPAT	OR	ON	2005/11/11 13:31
L43	9	("5664325").URPN.	USPAT	OR	ON	2005/11/11 13:36
L44	25	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) same (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin) and (resistor capacitor component) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 13:59
L45	26	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) same (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin) and (resistor capacitor component) with (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 14:00
L46	70	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) same (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin) and (resistor capacitor) and (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:07
L47	42	29/\$.ccls. and (print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin) and (resistor capacitor) and (embed\$4 encapsulat\$3)	USPAT; EPO; JPO	OR	ON	2005/11/11 14:04
L48	25	("4521262").URPN.	USPAT	OR	ON	2005/11/11 14:08

L49	16	("20010005304" "20010008479" "20020179329" "20030154592" "4063341" "4190854" "4528613" "4533974" "4906405" "5208597" "5256469" "5509200" "5557843" "6317023" "6426250" "6631551").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/11 14:26
L50	19	("20020179329" "20030154592" "4190854" "5099388" "5144526" "5378662" "5590017" "5745333" "6005197" "6021050" "6153290" "6184597" "6201684" "6215649" "6274224" "6317023" "6395996" "6597056" "6631551").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/11 14:29
L51	6	("20020179329" "20030154592" "4190854" "5227960" "6317023" "6631551").PN.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/11 14:29
L52	823	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (cur\$3 fir\$3) with (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:08
L53	3	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (cur\$3 fir\$3) with (reference mark fiducial) near4 (location position align\$4 register feature) with paste and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate) and (dielectric insulat\$3 resin)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:10
L55	53	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (cur\$3 fir\$3) with (ink paste (thick near1 film)) same (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:14
L57	52	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and (cur\$3 fir\$3) with (ink paste (thick near1 film)) with (reference mark fiducial) and (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:22

L62	90	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and tungsten with (reference mark fiducial) and (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:41
L63	7	62 and x\$1ray	USPAT; EPO; JPO	OR	ON	2005/11/11 15:25
L64	2	(print\$3 wir\$3 circuit) near2 (board substrate panel layer) and tungsten with (reference mark fiducial) with x\$1ray and (reference mark fiducial) near4 (location position align\$4 register feature) and (conduct\$3 metal\$4 copper cu) near2 (foil layer film plate)	USPAT; EPO; JPO	OR	ON	2005/11/11 15:41
L65	6	("4870746" "5708569" "5800575" "6610417" "6631551" "6734542").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/11 16:13
S1	3	borland.in. and x\$1ray.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/10 15:51
S2	29	x\$1ray same (print\$3 wir\$3 circuit) near2 (board substrate pannel layer) with (reference mark fiducial) near4 (location position)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/11/10 16:25